

- **SAW Filter for Digital Television**
- **Complies with Directive 2002/95/EC (RoHS)**



Characteristics:

Balance-to-balanced operation

Terminating source impedance : $Z_S = 200 \Omega$

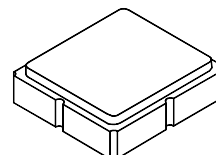
Terminating load impedance : $Z_L = 200 \Omega$

Maximum Rating

Rating	Value	Units
Input Power Level	0	dBm
DC Voltage on any Non-ground Terminal	3	V
Operating Temperature	-30 to +85	°C
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Suitable for Lead-free Soldering - Maximum Soldering Profile	260°C for 30 s	

SF2032E

1220 MHz SAW Filter



SM3030-8

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	f_C			1220		MHz
Insertion Loss, 1206 to 1234 MHz	IL			4.0	5.7	dB
Amplitude Ripple, 1206 to 1234 MHz				1.9	3.5	dB
Attenuation Referenced to 0 dB:						
300 to 1118 MHz			40	59		dB
1118 to 1146 MHz			45	60		
1300 to 2000 MHz			45	59		
Group Delay Ripple				15		nSp-p

Case Style	SM3030-8 3.0 x 3.0 mm Nominal Footprint					
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	504, YWWS					
Standard Reel Quantity	Reel Size 7 Inch	500 Pieces/Reel				
	Reel Size 13 Inch	3000 Pieces/Reel				

	Connection	Terminals
Port 1	Balanced Input	1,2
Port 2	Balanced Output	5,6
	Ground	All Others

Dot Indicates Pin 1

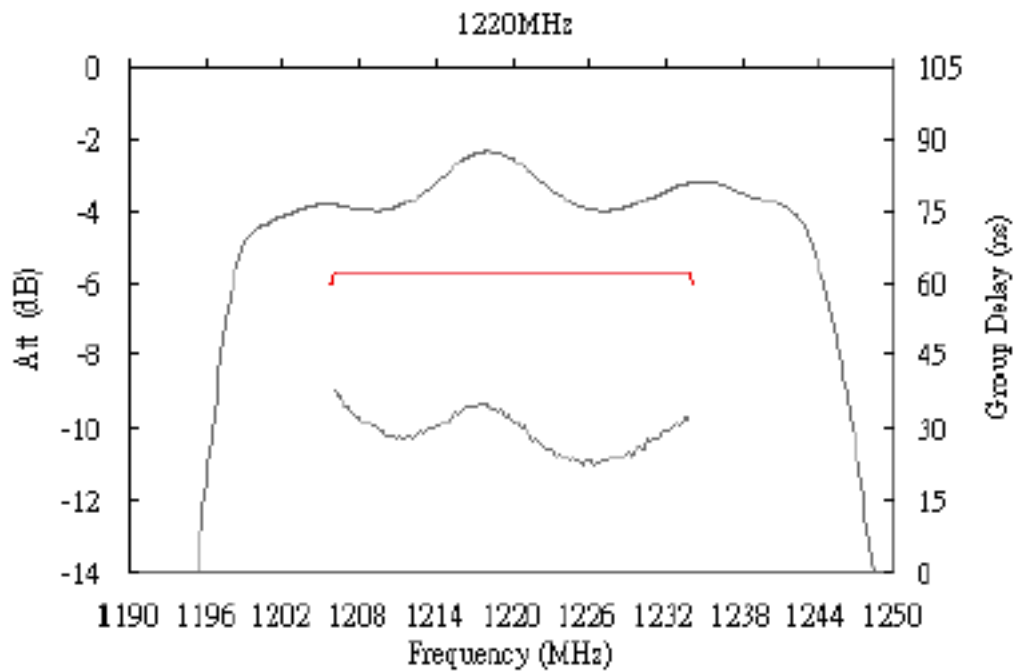
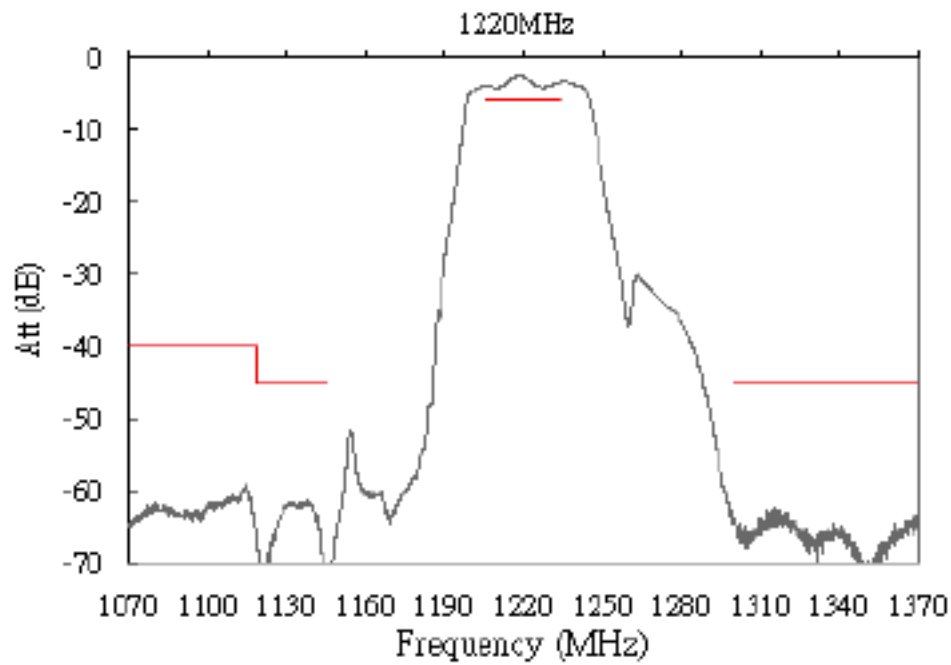


NOTES:

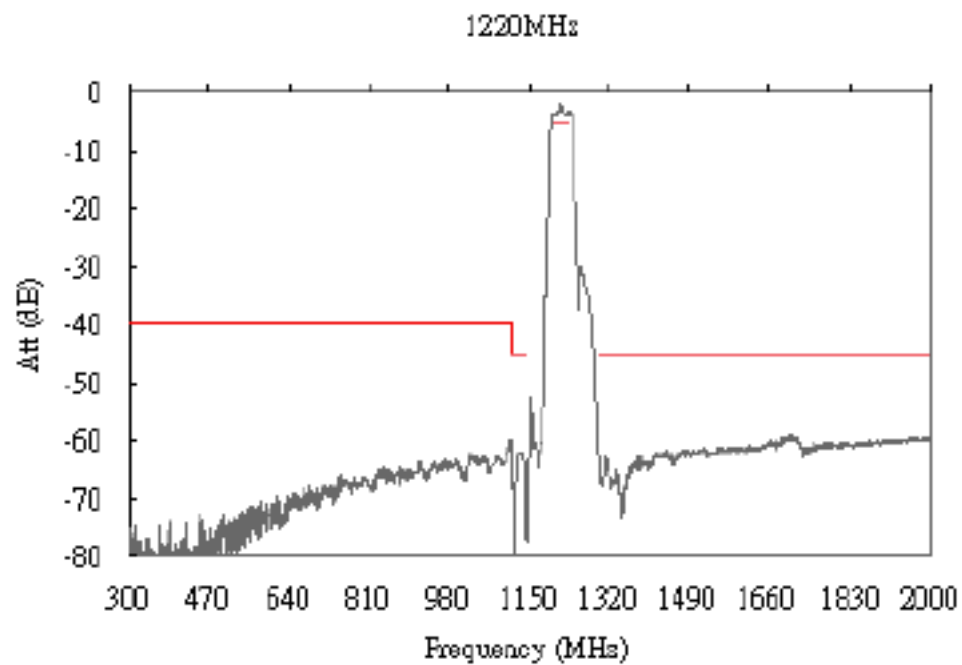
1. US and international patents may apply.
2. Murata, stylized Murata logo, and Murata N.A., Inc. are registered trademarks of Murata Manufacturing Co., Ltd.
3. Electrostatic Sensitive Device. Observe precautions for handling.

D. Transfer Function :

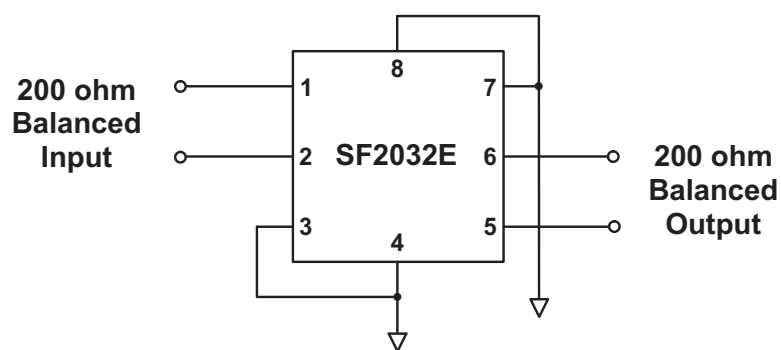
Narrowband



Wideband

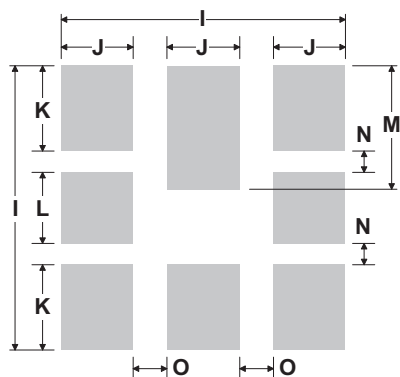
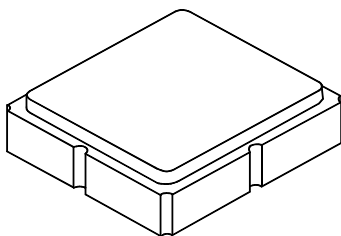


SF2032E Test Circuit



8-Terminal Ceramic Surface-Mount Case

3.0 X 3.0 mm Nominal Footprint



PCB Footprint Top View

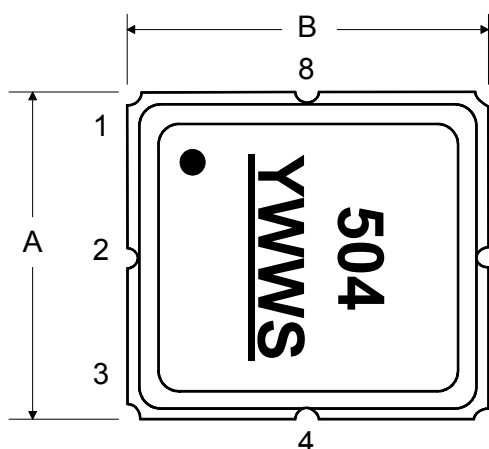
Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.0	3.13	0.113	0.118	0.123
B	2.87	3.0	3.13	0.113	0.118	0.123
C	1.14	1.27	1.40	0.045	0.050	0.055
D	0.79	0.92	1.05	0.031	0.036	0.041
E	0.62	0.75	0.88	0.024	0.029	0.034
F	0.47	0.60	0.73	0.018	0.024	0.029
G	0.47	0.60	0.73	0.018	0.024	0.029
H	1.07	1.20	1.33	0.042	0.047	0.052
I		3.19			0.126	
J		0.81			0.032	
K		0.96			0.038	
L		0.81			0.032	
M		1.39			0.055	
N		0.23			0.009	
O		0.38			0.015	

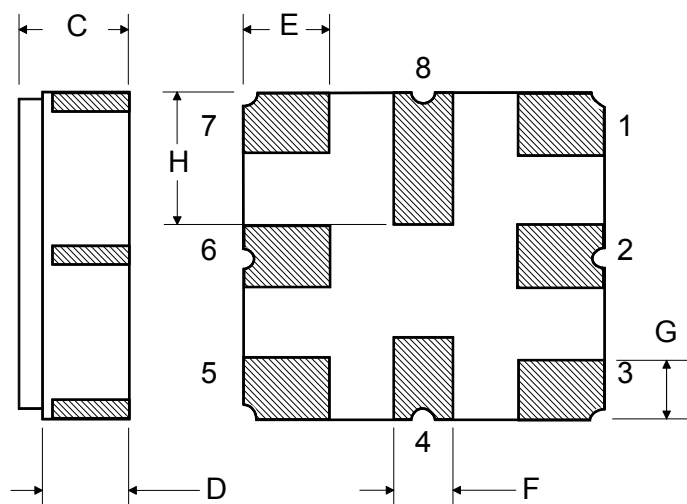
Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 μ m Gold over 1.27 to 8.89 μ m Nickel
Lid Plating	2.0 to 3.0 μ m Nickel
Body	Al ₂ O ₃ Ceramic
Pb Free	

TOP VIEW

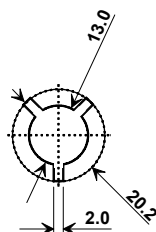


BOTTOM VIEW



Technical drawing showing a circular detail with a central hole. The drawing includes a top view (left) and a side view (right). The top view shows a large circle with a smaller concentric circle in the center, representing a hole. A vertical dashed line passes through the center of the circles. A leader line points from the text "See Detail 'A'" to the central hole. The side view shows two vertical rectangular sections. The left section is labeled "100 REF." and the right section is labeled "'B' REF.". A dimension line indicates a width of 12.0 for the right section.

“B” Nominal Size		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	3000



Carrier Tape Dimensions	
Ao	3.35 mm
Bo	3.35 mm
Ko	1.4 mm
Pitch	8.0 mm
W	12.0 mm

